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503.43552X00



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SHIBATA et al

Serial No.: 10/797,003

Filed: March 11, 2004

For: Mold Die And Method For Manufacturing Semiconductor  
Device Using The Same

Art Unit:

Examiner:

**AMENDMENT**

Mail Stop: Amendment (No Fee)  
Commissioner For Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

May 13, 2004

Sir:

The following amendments and remarks are respectfully requested in  
connection with the above-identified application as listed below and as set forth on  
the following pages:

Amendments to the Specification;

Amendments to the Claims;

Amendments to the Abstract;

Remarks are included following the amendments.